

C Series Heatsinks

Designed for TO-126, TO-220, TO-247 and TO-264 devices. This extruded Heatsink offers multiple lengths and sizes. Each extrusion utilizes our patented clipping system. This system requires no tools and can lock in the device with one finger. The cam-locking system engages the device securely for a proper thermal connection. The C Series from Ohmite is the ideal type of Heatsink for high power density and small size (1U or 2U) electronic packaging with forced convection cooling.



D Series Heatsinks

These surfacemount Heatsinks are extruded, not stamped. This extruded design is far more efficient than any stamped counterpart. One of the main issues is getting heat from the board level into the Heatsink. The extrusion allows for large pads and a direct thermal path from the board and into the Heatsink. The ability to get the heat off the board coupled with its large surface area yields a surfacemount Heatsink unmatched in the market.



E Series Heatsinks

The Ohmite E Series is offered in multiple extrusion lengths and is black anodized to provide great thermal performance in natural convection applications. This extrusion form can be used for TO-220 devices and provides a thermal resistance as low as 6.2° C/W. For use with Ohmite part Series TBH25 and TCH35. These Heatsinks can also be used for other power devices requiring thermal assistance.

P Series Heatsinks

The new P Series Heatsink from Ohmite uses Forged Pin technology. The forged pins increase the surface area for greater free air convection. Forced air convection applications will benefit from the ability to force air in multiple directions through the pins. This creates versatility as the designer is no longer stuck forcing air in a single direction. Designed for TO-126, TO-220, TO-247, and TO-264 devices. Each Heatsink utilizes the patented clipping system. This system requires no tools and can lock in the device with one finger. The cam-locking system engages the device securely for a proper thermal connection. The P Series from Ohmite is the ideal type of Heatsink for high power density and small size (1U or 2U) electronic packaging with forced convection cooling.



TO-247 and Large Heat Sinks

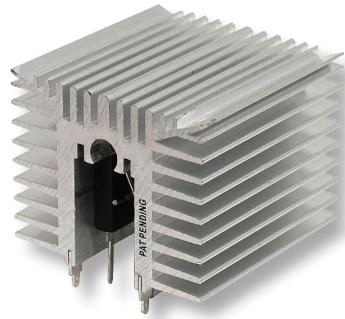
Since Ohmite offers a selection of TO-247 and larger devices in heat sinkable packages, it is no surprise that Ohmite can provide thermal solutions for these devices in multiple sizes and configurations to accommodate many application needs and designs. Ohmite also offers standard screw mount and patented clipping systems for these devices. Custom options are available in many product Series, including expandable options and multiple extrusion lengths to accommodate these larger devices.

OHMITE®



R2 Series Heatsinks

Ohmite's R2 Series (patent pending) Heatsink provides a large surface area along with our C Series Clipping Mechanism to attach to a TO-220, TO-247, or TO-264 package. The self-aligning features of the clip assure secure attachment and enhanced thermal performance. Because no screws are required for device mounting, additional fins can be added to the rear side of the Heatsink for increased total surface area in a more compact space. The R2 Series mounts vertically and has integrated solderable feet for easy mounting. The R2 Series is available in degreased and anodized versions for even more thermal performance.

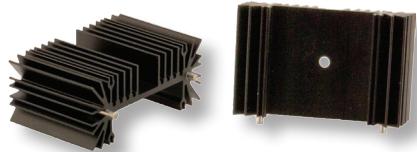


M Series Heatsinks

Ohmite introduces the patented M Series. The multiple advantages of this Ohmite M Series Heatsink are high performance, low cost, configurability, scalability, and compact design. The M Series Heatsink with matrix clip system for TO-247 and TO-264 packages eliminates the use of fastener hardware. This powerful heat sink provides the easiest assembly, largest surface area, and smallest footprint. It is the ideal type of Heatsink for high power density and small size (1U or 2U) electronic packaging with forced convection cooling. Ohmite provides the M Series in multiple extrusion lengths and two different forms.

VM Series Heatsinks

Ohmite introduces this new versatile Heatsink design with the VM Series Heatsink. This new design can accommodate several different industry packages. The VM Series also lets the customer choose a mounting style using screws or clips for secure mounting to the Heatsink. These one-of-a-kind Heatsinks are offered in a vertical (free convection cooling) or horizontal (forced convection cooling) format to fit customer applications. For the engineer still in a prototype phase, Ohmite offers a universal mounting option. This option includes both sets of feet for vertical or horizontal mounting.



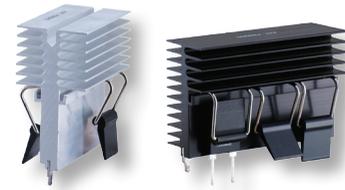
WC Series Heatsinks

The WC Series is produced using high purity ceramic. The WC is non-conductive producing electrical isolation for high voltage devices. Aluminum heatsinks require isolating materials to achieve the same result as the WC Series. The WC Series Ceramic Heatsink is ideal for applications using high voltage TO packaged devices.



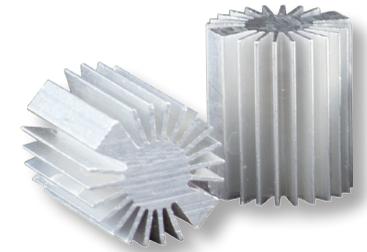
CA Series Heatsinks

The CA Series is a Ceramic Heatsink capable of handling two devices. This dual Ceramic Heatsink utilizes the same patented cam lock clips used in many Ohmite Heatsinks. This clip system requires no tools or fixtures for assembling devices to the Heatsink. The CA Series is mounted to the PCB via through-hole solderable feet.



CR Series Heatsinks

Ohmite introduces the CR Series Heatsink with cam clip (patent pending). The CR Series offers flexibility, high performance, and is comparable to popular Aavid MAX-clip heatsinks. The cam clip system for TO-247 and TO-264 devices is proprietary and provides tool- or fixture-free assembly. The CR Series is available in multiple extrusion lengths to support up to three devices and is available in black anodized or degreased finishes.



SV Series Heatsinks

Ohmite introduces the SV-LED Series. The SV Series is a high performance, low cost, configurable, scalable, and compact Heatsink for LED modules. This powerful high aspect ratio Heatsink comes in two standard heights. Each SV Series Heatsink can be configured to customer specifications. Customers can specify length, surface finish, mounting holes, and custom machining.

CSM Series Heatsinks

The CSM Series is suitable for use with a variety of TO-type devices found in active components as well as power resistors. With surface areas ranging from 1,188 sq. mm to 6,645 sq. mm, the CSM family comes in five configurations, all of them with black anodized surface treatment. These Heatsinks offer a range of thermal performance from 18.0 to 9.8° C/W. Each device offers solderable mounting feet and anywhere from one, two or three mounting holes are available for convenient device attachment.

